IN THE SPECIFICATION:

Please amend paragraph 0026, as follows:

[0026] In one embodiment, which is illustrated in FIGS. 5A-5B, the islands 255 are selectively deposited on the conductors 233u using any suitable deposition method, such as contact displacement plating, electroless plating, or electroplating. The discontinuous nature of metal interlayer 250 results, at least in part, from the fact that sufficiently thin films can be unstable. In addition, to avoid interdiffusion between the metal interlayer 250 and the underlying conductors 233u, it is desirable that the metal interlayer (e.g., Silver) and the conductor metal (e.g., Copper) be insoluble. This insolubility – or, more precisely, very low solubility – is illustrated in the Cu-Ag phase diagram 800 of FIG. 8 (e.g., for a Silver interlayer and Copper conductor combination). Referring to this figure, the weight percent of Silver 820 and the weight percent of Copper 830 (on horizontal axis) are shown as a function of temperature 810 (vertical axis). At temperatures of approximately 300° C (see curve 890) and less, there is no appreciable mixing between Copper and Silver. If the Silver does not diffuse into the Copper and the Silver interlayer is sufficiently thin (approximately 10 to 5,000 Angstroms in one embodiment), this thin Silver interlayer will agglomerate into small islands due to surface instabilities (which are influenced by factors such as grain boundaries, interface energy, and surface energy). Although the preceding discussion is presented using the example of Silver and Copper, those of ordinary skill in the art will appreciate that ~~may~~ **many** other metal combinations can produce this island morphology, as noted above.